



N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^{a, b}	Q _g (Typ.)		
30	0.026 at V _{GS} = 10 V	8	4.2		
	0.032 at V _{GS} = 4.5 V	8	4.2		

FEATURES

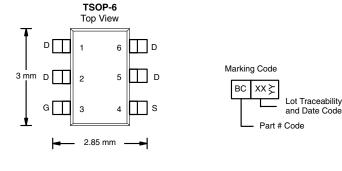
- Halogen-free According to IEC 61249-2-21
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

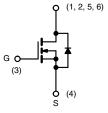


HALOGEN **FREE**

APPLICATIONS

- · Load Switch for Portable Devices
- DC/DC Converters





Ordering Information: Si3424CDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, un	less otherwise n	oted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		8 ^a		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	L .	7.7		
Continuous Diam Current (1) = 130 °C)	T _A = 25 °C	I _D	7.2 ^{c, d}	A	
	T _A = 70 °C		5.7 ^{c, d}		
Pulsed Drain Current (t = 300 μs)		I _{DM}	20		
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	3	^	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.7 ^{c, d}	A	
	T _C = 25 °C		3.6		
Maximum Dawar Dissination	T _C = 70 °C	PD	2.3	w	
Maximum Power Dissipation	T _A = 25 °C	LD	2.0 ^{c, d}		
	T _A = 70 °C		1.3 ^{c, d}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^e	t ≤ 5 s	R_{thJA}	50	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	28	35		

Notes:

- a. Package limited.
- b. Based on $T_C = 25$ °C.
- c. Surface mounted on 1" x 1" FR4 board.
- d. t = 5 s.
- e. Maximum under steady state conditions is 110 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				, ,			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 - A		28		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 3.7			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Wallana Busin Ourmant		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1 ,		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
	D.	$V_{GS} = 10 \text{ V}, I_D = 7.2 \text{ A}$		0.021	0.026	 	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 6.5 \text{ A}$		0.026	0.032	Ω	
Forward Transconductance	9 _{fs}	V _{DS} = 15 V, I _D = 7.2 A		17		S	
Dynamic ^b			•				
Input Capacitance	C _{iss}			405		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		92			
Reverse Transfer Capacitance	C _{rss}			42			
Tatal Oata Obarra	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.2 \text{ A}$		8.3	12.5		
Total Gate Charge				4.2	6.3	20	
Gate-Source Charge	Q_{gs}	$V_{DS} = 24 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 7.2 \text{ A}$		1.2		nC	
Gate-Drain Charge	Q_{gd}			1.6			
Gate Resistance	R_g	f = 1 MHz	0.6	3	6	Ω	
Turn-On Delay Time	t _{d(on)}			3	6		
Rise Time	t _r	V_{DD} = 15 V, R_L = 2.6 Ω		12	20		
Turn-Off DelayTime	t _{d(off)}	$I_D \approx 5.7 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	24		
Fall Time	t _f			8	16	no	
Turn-On Delay Time	t _{d(on)}			10	20	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 2.6 Ω		22	33		
Turn-Off DelayTime	t _{d(off)}	$I_D \approx 5.7 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		15	23		
Fall Time	t _f			9	18		
Drain-Source Body Diode Characteris	tics						
Continous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			3	Α	
Pulse Diode Forward Current ^a	I _{SM}				20		
Body Diode Voltage	V _{SD}	I _S = 5.7 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			13	20	nC	
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = 5.7 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		5	10	ns	
Reverse Recovery Fall Time	t _a	$I_F = 0.7$ A, $I_F = 100$ A/ μ S		8			
Reverse Recovery Rise Time	t _b			5			

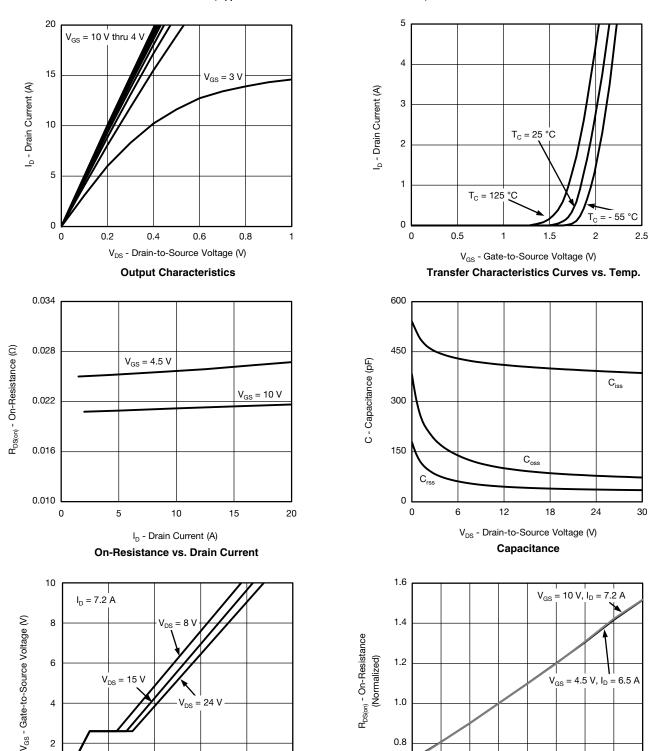
Notes:

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Document Number: 67443 S11-0863-Rev. A, 02-May-11

2

0

0

2

Q_q - Total Gate Charge (nC)

Gate Charge

125

100

50

T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

150

10

0.8

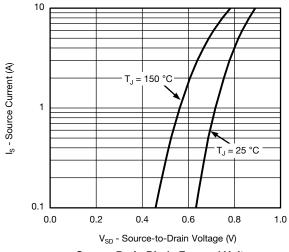
0.6

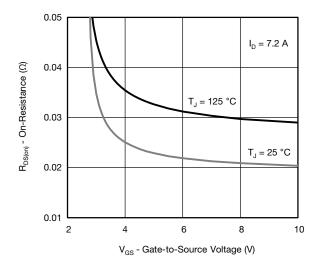
- 50

- 25

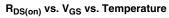
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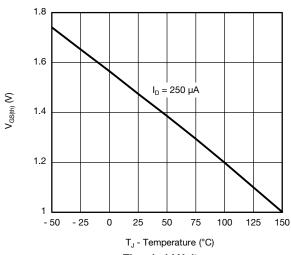
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

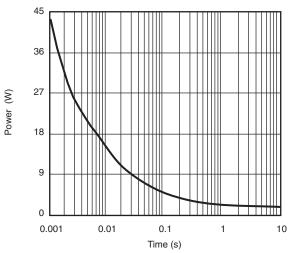




Source-Drain Diode Forward Voltage

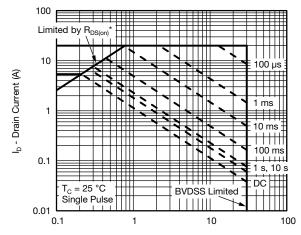






Threshold Voltage

Single Pulse Power

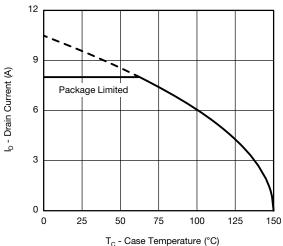


V_{DS} - Drain-to-Source Voltage (V) * $V_{\text{GS}} > \text{minimum } V_{\text{GS}}$ at which $R_{\text{DS(on)}}$ is specified

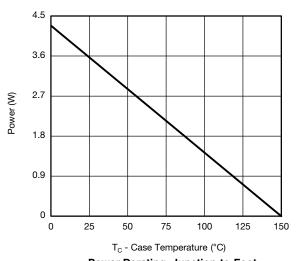
Safe Operating Area, Junction-to-Ambient

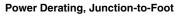


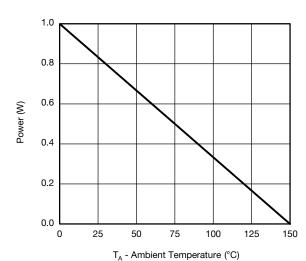
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Current Derating*







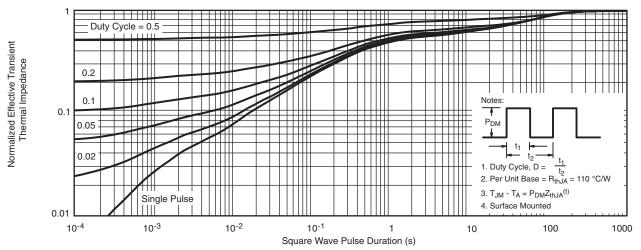
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

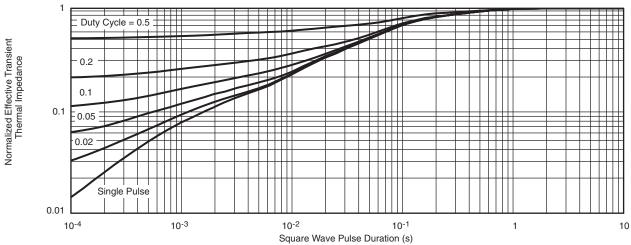
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TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

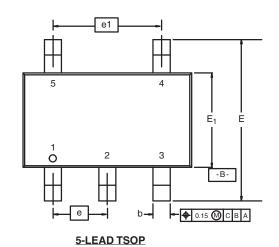
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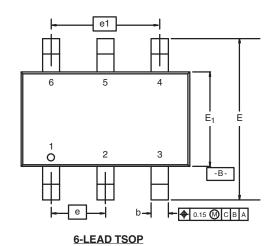


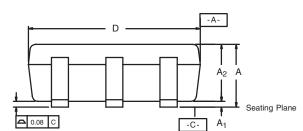


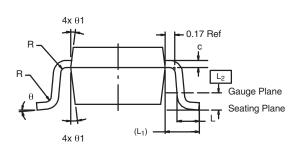
TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C









	MIL	LIMETER	RS	INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.91	-	1.10	0.036	-	0.043
A ₁	0.01	-	0.10	0.0004	-	0.004
A ₂	0.90	-	1.00	0.035	0.038	0.039
b	0.30	0.32	0.45	0.012	0.013	0.018
С	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
E	2.70	2.85	2.98	0.106	0.112	0.117
E ₁	1.55	1.65	1.70	0.061	0.065	0.067
е	0.95 BSC			0.0374 BSC		
e ₁	1.80	1.90	2.00	0.071 0.075		0.079
L	0.32	-	0.50	0.012	-	0.020
L ₁	0.60 Ref			0.024 Ref		
L ₂	0.25 BSC			0.010 BSC		
R	0.10	-	-	0.004	-	-
θ	0°	4°	8°	0°	4°	8°
θ_1	7° Nom			7° Nom		
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